

COPPER-NICKEL ALLOY ELECTROPLATING BATH

Abstract

5 The present invention provides a copper-nickel alloy electroplating bath which contains (a) a copper salt and a nickel salt, (b) a metal complexing agent, (c) a conductivity imparting agent, (d) a sulfur-containing organic compound and (e) a redox potential regulator.

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[No Suitable Figure]